

Call for Papers

Special Focus on Artificial Intelligence Innovation in Remote Sensing



SCIENCE CHINA Information Sciences (SCIS) calls for papers for a Special Focus on Artificial Intelligence (AI) Innovation in Remote Sensing (RS). Recently, AI plays a growing role in remote sensing, which has been exponentially increasing interests in research of deep learning as applied in remote sensing image processing, including optical satellite images, hyperspectral images, and radar images. It is fair to say that, the AI technique and a flood of valuable data coming from different RS sensors give us a possible to enable the learning-based “data model” outside of the traditional ones. This special issue focuses on recent progress in developing AI methodology with a variety of remote sensing applications including but not limited to:

- SAR/Hyperspectral image processing and information retrieval
- AI-based InSAR signal processing and information retrieval
- Target detection and recognition in RS images
- Parameter inversion in RS images
- RS image classification and segmentation
- Learning algorithms and models of RS dataset (supervised/weakly-supervised/unsupervised)
- Fusion framework of the datasets from disparate RS sensors
- AI application using datasets from GF satellite

Submission

The papers should be edited in the SCIS template, and should be submitted online through the manuscript submission system of the *SCIENCE CHINA Information Sciences*. The submission website is: <https://mc03.manuscriptcentral.com/scis>. You should choose **Special Focus on Artificial Intelligence Innovation in Remote Sensing**. Information and guidelines on preparation of manuscripts are available on the journal website: <http://scis.scichina.com>.

Important Dates

Submission deadline: August 31, 2022

Acceptance notification: December 30, 2022

Final manuscripts due: January 15, 2023

Publication: May 1, 2023

Guest Editors

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